

### **Description**

The AP90P01D uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

#### **General Features**

V<sub>DS</sub>=12V I<sub>D</sub> =90A

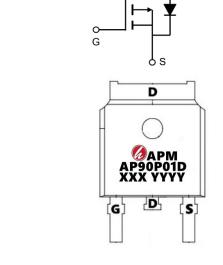
 $R_{DS(ON)} < 4.5 \text{m}\Omega$  @  $V_{GS}$ =4.5V (Type: 3.5 $\text{m}\Omega$ )

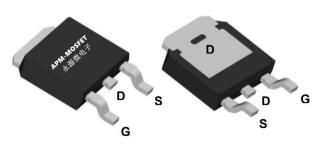
### **Application**

Battery protection

Load switch

Uninterruptible power supply





Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)	
AP90P01D	TO-252-3L	AP90P01D XXX YYYY	2500	

#### Absolute Maximum Ratings (T<sub>C</sub>=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	-12	V
VGS	Gate-Source Voltage	±12	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	-90	А
I <sub>D</sub> @T <sub>C</sub> =100°C	Γ <sub>C</sub> =100°C Continuous Drain Current, V <sub>GS</sub> @ 10V¹		А
IDM	Drain Current – Pulsed1	-240	Α
IAS	Avalanche Current	50	Α
EAS	Single Pulsed Avalanche Energy	560	mJ
TJ, TSTG	Operating and Storage Temperature Range	-55 to 150	°C
RθJA	Thermal Resistance Junction to ambient	62.5	°C/W
RθJC	Thermal Resistance Junction to Case	3	°C/W





### Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	VGS=0V , ID=-250uA	-12	-18		V
∆BVDSS/∆TJ	BVDSS Temperature Coefficient	Reference to 25°C , ID=-1mA		-0.008		V/°C
DD0(01)		VGS=-4.5V , ID=-20A		3.5	4.5	
RDS(ON)	Static Drain-Source On-Resistance	VGS=-2.5V , ID=-20A		4.8	6.0	mΩ
VGS(th)	Gate Threshold Voltage		-0.4	-0.6	-1.0	V
∆VGS	VGS(th) Temperature Coefficient	VGS=VDS , ID =-250uA		-3.44		mV/°C
IDOO		VDS=-20V , VGS=0V , TJ=25°C			-1	uA
IDSS	Drain-Source Leakage Current	Current VDS=-16V ,VGS=0V ,TJ=125°C			-30	uA
IGSS	Gate-Source Leakage Current	VGS=±12V , VDS=0V			±500	nA
gfs	Forward Transconductance	VDS=-10V , IS=-3A		30		S
Qg	Total Gate Charge			149	225	
Qgs	Gate-Source Charge	VDS=-16V , VGS=-4.5V , ID=- 5A		14.4	22	
Qgd	Gate-Drain Charge	JA		42.8	65	nC
Td(on)	Turn-On Delay Time			21.2	42	
Tr	Rise Time	VDD=-15V , VGS=-4.5V ,		20.6	40	
Td(off)	Turn-Off Delay Time	RG=25□ ID=-1A		26	52	nS
Tf	Fall Time	, .		400	600	
Ciss	Input Capacitance			6800		
Coss	Output Capacitance	VDS=-15V , VGS=0V , F=1MHz		769		pF
Crss	Reverse Transfer Capacitance			726		
Rg	Gate resistance	VGS=0V, VDS=0V, F=1MHz		2.6		Ω
IS	Contineous Source Current	V VI 0/ 5			-90	
ISM	Pulsed Source Current	Vg=Vd=0V, Force Current			-180	Α
VSD	Diode Forward Voltage	Vgs=0V Is=1A Tj=25°C			-1	V

#### Note:

- 1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- $2_{\times}$  The data tested by pulsed , pulse width  $\leqq$  300us , duty cycle  $\leqq$  2%
- 3、The EAS data shows Max. rating . The test condition is VDD=8V,VGS=4.5V,L=0.1mH,IAS =50A
- 4. The power dissipation is limited by 150  $^{\circ}\mathrm{C}$  junction temperature
- 5. The data is theoretically the same as I D and I DM, in real applications, should be limited by total power dissipation.



### **Typical Characteristics**

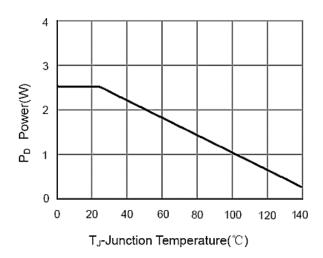


Figure 1: Power Dissipation

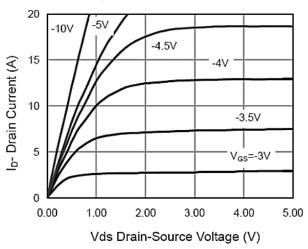


Figure 3: Output Characteristics

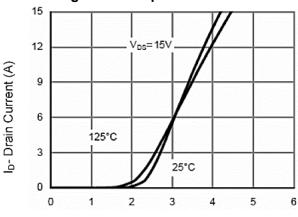


Figure 5: Transfer Characteristics

Vgs Gate-Source Voltage (V)

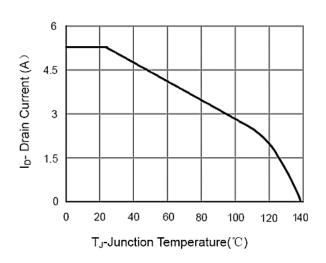


Figure 2: Drain Current

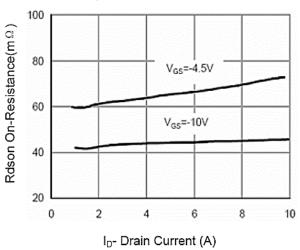


Figure 4: Drain-Source On-Resistance

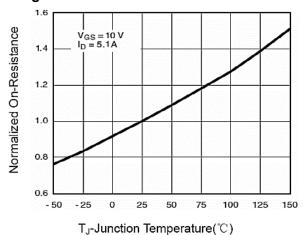
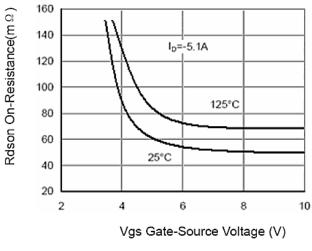


Figure 6: Drain-Source On-Resistance







600 Ciss C Capacitance (pF) 450 300 150  $C_{rss}$ 0 5 10 15 20 25 0 30 Vds Drain-Source Voltage (V)

Figure 7: Rdson vs Vgs

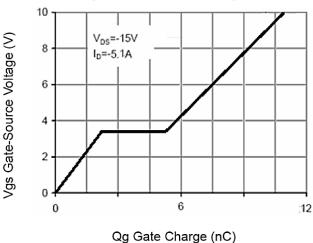


Figure 8: Capacitance vs Vds

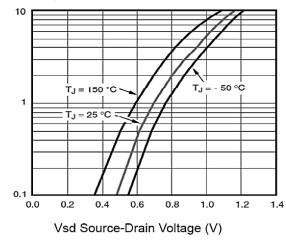
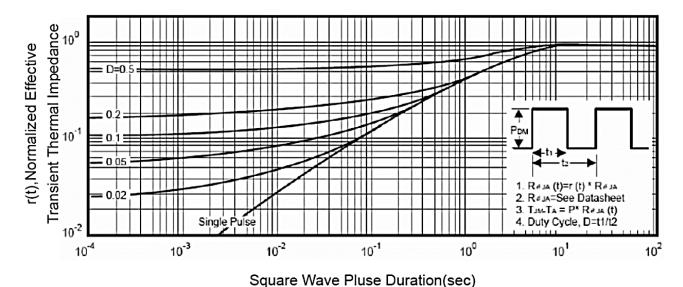


Figure 9: Gate Charge

Figure 10: Sourece-Drain Diode Forward

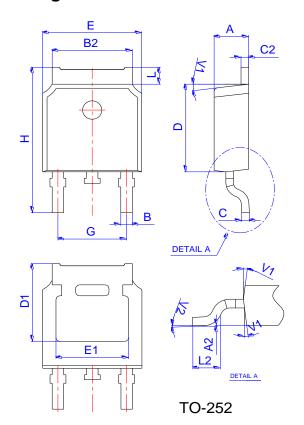


Is- Reverse Drain Current (A)

Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

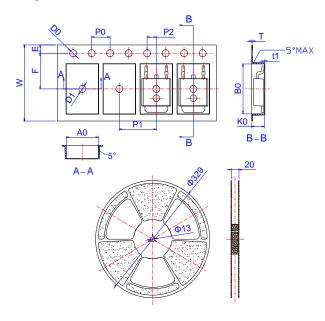


# Package Mechanical Data:TO-252-3L



Dimensions							
Ref.	Millimeters			Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
Α	2.10		2.50	0.083		0.098	
A2	0		0.10	0		0.004	
В	0.66		0.86	0.026		0.034	
B2	5.18		5.48	0.202		0.216	
С	0.40		0.60	0.016		0.024	
C2	0.44		0.58	0.017		0.023	
D	5.90		6.30	0.232		0.248	
D1		5.30REF		0.209REF			
E	6.40		6.80	0.252		0.268	
E1	4.63			0.182			
G	4.47		4.67	0.176		0.184	
Н	9.50		10.70	0.374		0.421	
L	1.09		1.21	0.043		0.048	
L2	1.35		1.65	0.053		0.065	
V1		7°			7°		
V2	0°		6°	0°		6°	

# **Reel Spectification-TO-252**



	Dimensions						
Ref.	Millimeters			Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
W	15.90	16.00	16.10	0.626	0.630	0.634	
Е	1.65	1.75	1.85	0.065	0.069	0.073	
F	7.40	7.50	7.60	0.291	0.295	0.299	
D0	1.40	1.50	1.60	0.055	0.059	0.063	
D1	1.40	1.50	1.60	0.055	0.059	0.063	
P0	3.90	4.00	4.10	0.154	0.157	0.161	
P1	7.90	8.00	8.10	0.311	0.315	0.319	
P2	1.90	2.00	2.10	0.075	0.079	0.083	
A0	6.85	6.90	7.00	0.270	0.271	0.276	
В0	10.45	10.50	10.60	0.411	0.413	0.417	
K0	2.68	2.78	2.88	0.105	0.109	0.113	
T	0.24		0.27	0.009		0.011	
t1	0.10			0.004			
10P0	39.80	40.00	40.20	1.567	1.575	1.583	





## **AP90P01D**

#### 12V P-Channel Enhancement Mode MOSFET

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# **AP90P01D**

## 12V P-Channel Enhancement Mode MOSFET

Edition	Date	Change
Rve1.0	2020/5/1	Initial release

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